

4

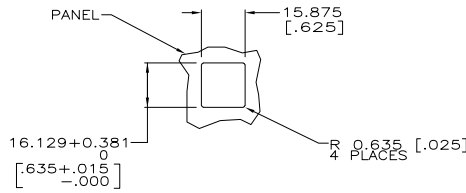
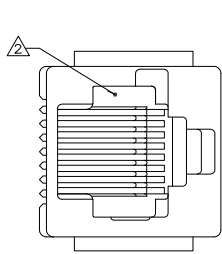
3

2

1

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LOC	DIST	REVISIONS			
F	LR	DESCRIPTION	DATE	BY	APP'D
AA	22	A	REV PER EC 0511-0201-04	06/JUN/2005	GA SF

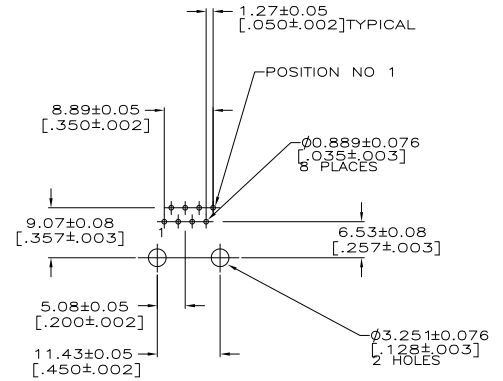
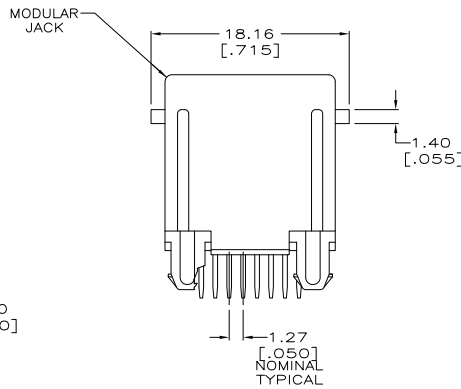
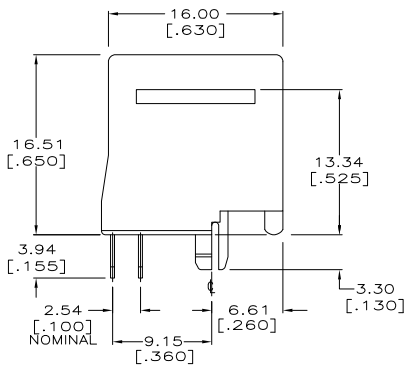


PANEL CUTOUT  
SCALE 1:1

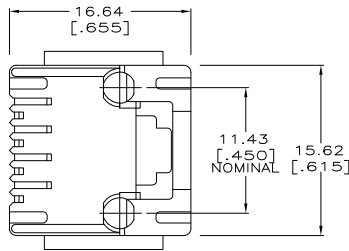
1 MATERIAL: HOUSING - PBT POLYESTER, BLACK.  
 TERMINAL - 0.36 [.014] THICK PHOS BRONZE  
 PLATED WITH 1.27μm [.000050] MINIMUM THICK HARD  
 GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm  
 [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER  
 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.

2 CAVITY CONFORMS TO FCC RULES AND  
 REGULATIONS PART 68 AND REA BULLETIN  
 345-81, PE-76 SPECIFICATION FOR MODULAR  
 TELEPHONE HARDWARE.

3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS  
 OTHERWISE SPECIFIED.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 COMPONENT SIDE  
 SCALE 2:1



8		5520260-4	
CONTACTS		PART NUMBER	
Tyco Electronics Corporation Harrisburg, Pa 17105-3608			
PRINTED CIRCUIT BOARD MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, KEYED, FLANGELESS, WITH PANEL STOPS			
A200779		C-5520260	
CUSTOMER DRAWING		SCALE	1:1
		SHEET	1 OF 1
		REV	A

5520260

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